

### Features:

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

### Typical Applications

- Inverter
- Inductive heating
- Chopper

V <sub>RSM</sub>	V <sub>RRM</sub>	品名
900V	800V	Mx400DF80W
1100V	1000V	Mx400DF100W
1300V	1200V	Mx400DF120W
1500V	1400V	Mx400DF140W
1700V	1600V	Mx400DF160W

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>j</sub> (°C)	VALUE			UNIT
				Min.	Typ.	Max.	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave 50Hz Single side cooled, T <sub>c</sub> =60°C	150			400	A
I <sub>F(RMS)</sub>	RMS forward current					628	A
I <sub>RRM</sub>	Repetitive peak current	at V <sub>RRM</sub>	150			40	mA
I <sub>FSM</sub>	Surge forward current	10ms half sine wave V <sub>R</sub> =0.6V <sub>RRM</sub>	150			8.30	kA
I <sup>2</sup> t	I <sup>2</sup> t for fusing coordination					344	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>FO</sub>	Threshold voltage		150			1.0	V
r <sub>F</sub>	Forward slope resistance					0.85	mΩ
V <sub>FM</sub>	Peak forward voltage	I <sub>FM</sub> =1200A	25			2.1	V
t <sub>rr</sub>	Reverse recovery time	I <sub>FM</sub> =300A, tp=2000μs, -di/dt=20A/μs, V <sub>R</sub> =50V	150		4.0		μs
R <sub>th(j-c)</sub>	Thermal resistance Junction to case	D.C. Single side cooled per chip				0.130	°C/W
R <sub>th(c-h)</sub>	Thermal resistance case to heatsink	D.C. Single side cooled per chip				0.040	°C/W
F <sub>m</sub>	Terminal connection torque(M10)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
T <sub>vj</sub>	Junction temperature			-40		140	°C
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight				1560		g
Outline	M14						

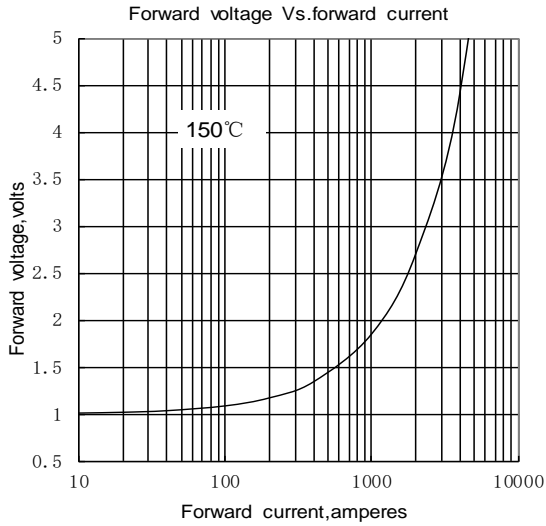


Fig.1

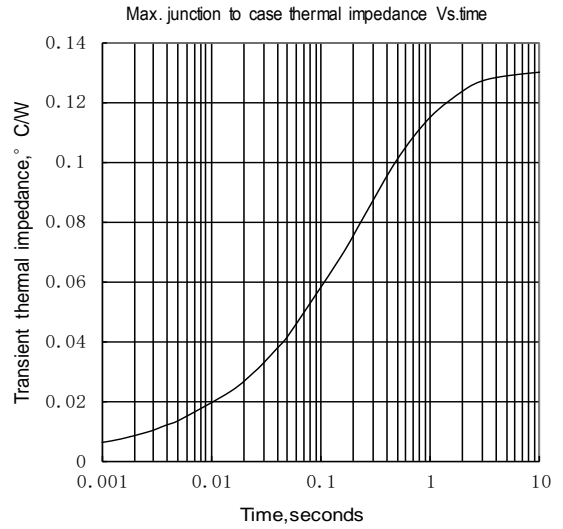


Fig.2

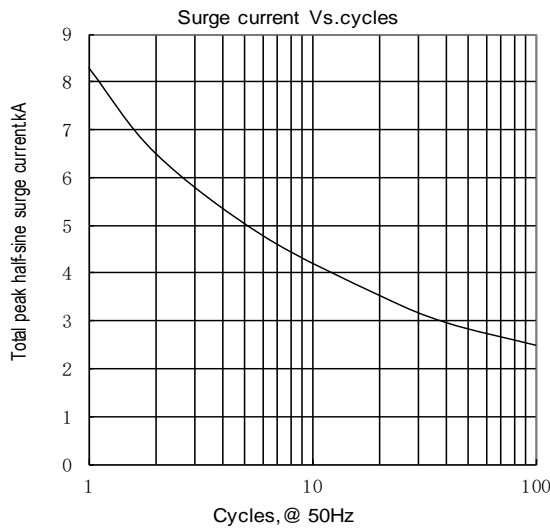
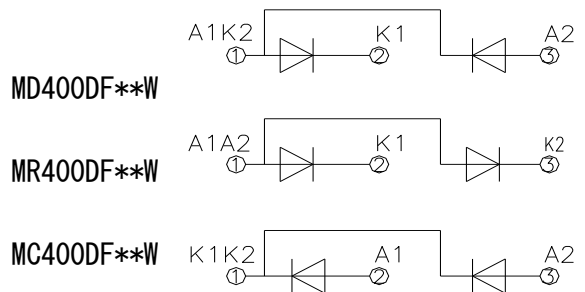
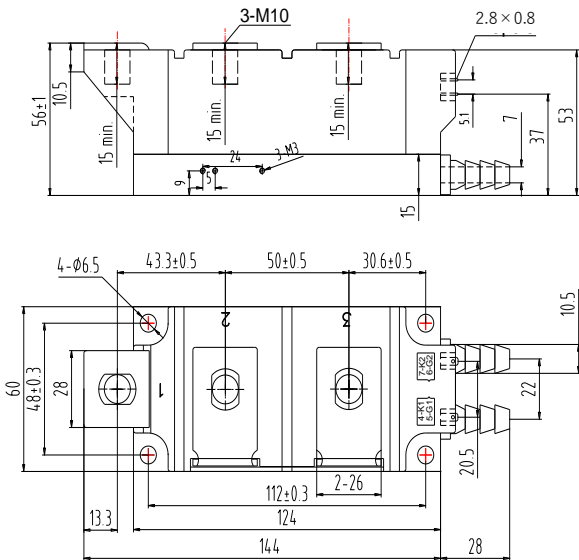


Fig.3



Unmarked dimensional tolerance : ±0.5mm